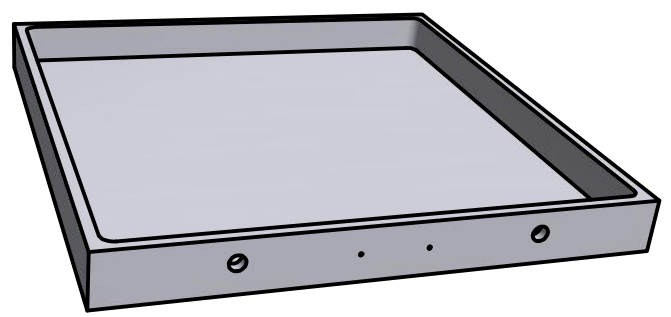
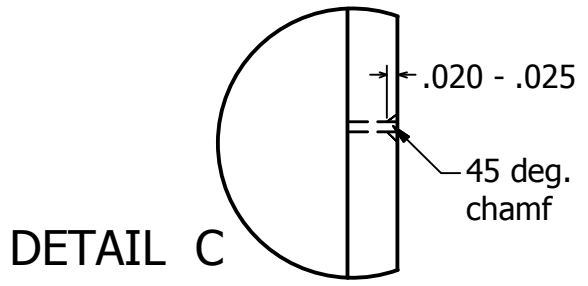
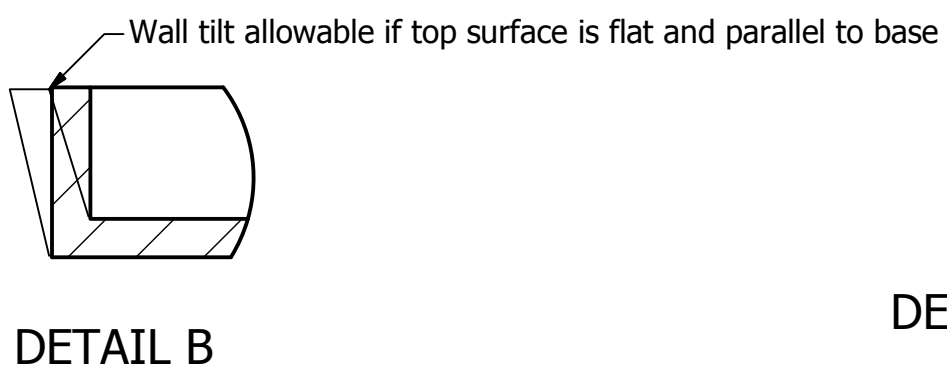


Rev.A Pin hole dia. increased from .042 to .044 11.30.16 RN
 Rev.B Pin hole dia. changed to .043 - .046 , chamf. added, and notes 3 & 4 added 3.21.17 RN
 Rev.C Add top surface grinding spec;change height tolerance to +.007 - 0;reword note 4 on chamfer.
 Rev.D Top surface note changed to "Top surface to be flat. Surface finish to be < / = 20 micro-inches." 6.5.17 RN



Notes-

1. Tile base to be made of full-fired alumina 96% pure or higher.
2. Tile base to be hermetic in helium leak-test at UC to $5 \times 10E - 10CC/SEC$.
3. To facilitate hermetic sealing of the pins during assembly air-firing at ~ 1600 C for 2-4 hrs. may eliminate micro-cracking due to grinding.
4. In the case that this ceramic part is a component of an order for the complete brazed assembly (CeramTBAssm081015ReVA or equivalent) , the chamfer on the holes for the pins on the outside of the wall (see Detail C) is at the discretion of the brazing house. Otherwise we require implementing the chamfer.



DRAWN rnorthrop	11/10/2015	University of Chicago		
CHECKED				
QA		TITLE Green Trim Ceramic Tile Base		
MFG				
APPROVED		SIZE B	DWG NO CeramTB111015revD	REV D
		SCALE	SHEET 1 OF 1	